



The Electronics Division Hoffman Scholarship Application Form

2017 Essay Topic:

**Low Dimensional Structures and Properties in Electronic Ceramics**

Application Deadline: May 15<sup>th</sup> annually

Full Name \_\_\_\_\_

Email Address \_\_\_\_\_

Mailing Address \_\_\_\_\_  
\_\_\_\_\_  
\_\_\_\_\_

Name of Undergraduate Department \_\_\_\_\_

University \_\_\_\_\_

Total GPA \_\_\_\_\_ Science GPA \_\_\_\_\_ Total Credits \_\_\_\_\_

PSAT/SAT/ACT Scores \_\_\_\_\_ Date of Exam \_\_\_\_\_

Extracurricular Activities \_\_\_\_\_  
(attach additional sheets if necessary)  
\_\_\_\_\_  
\_\_\_\_\_

Faculty Advisor\* \_\_\_\_\_  
Address \_\_\_\_\_  
\_\_\_\_\_

Telephone ( ) \_\_\_\_\_ E-mail \_\_\_\_\_

Applicant's Signature \_\_\_\_\_ Date \_\_\_\_\_

Advisor's Signature \_\_\_\_\_ Date \_\_\_\_\_

\* Essay and Recommendation letter must be emailed directly to:

Alp Sehrioglu  
Department of Materials Science and Engineering  
Case Western Reserve University  
[alp.sehrioglu@case.edu](mailto:alp.sehrioglu@case.edu)  
216-368-1987

Nominations should also be sent to Erica Zimmerman at [EZimmerman@ceramics.org](mailto:EZimmerman@ceramics.org)